Local Government Infrastructure Financing Program Expression of Interest

NAME OF LOCAL GOVERNMENT						
There is reasonable probability that we may participate in a future Local Government Infrastructure Program Bond Issuance, for a loan of approximately \$ to finance (or refinance) the following project(s).						
We will download the application and the instructions from www.dhcd.state.md.us .						
Please send hard copies of the application package.						
Please come visit to explain the Program to our:						
governing body staff other:						
Please send more detailed information about the program.						
To facilitate communications about the progress of the program's next financing and about the details of future financings, please use this e-mail address for us:						
Other:						
CONTACT:						
	Name o	of Local Govern	ment Official		Date	
Title			Phone		E-Mail	
PLEAS	E MAIL TO:	100 Commun	nfrastructure P nity Place, Roor ID 21032-2023	m 4.435		
OR FAX	X TO:	410-987-8763				
		Larry Hogan		Boyd K.	Rutherford	

Governor

